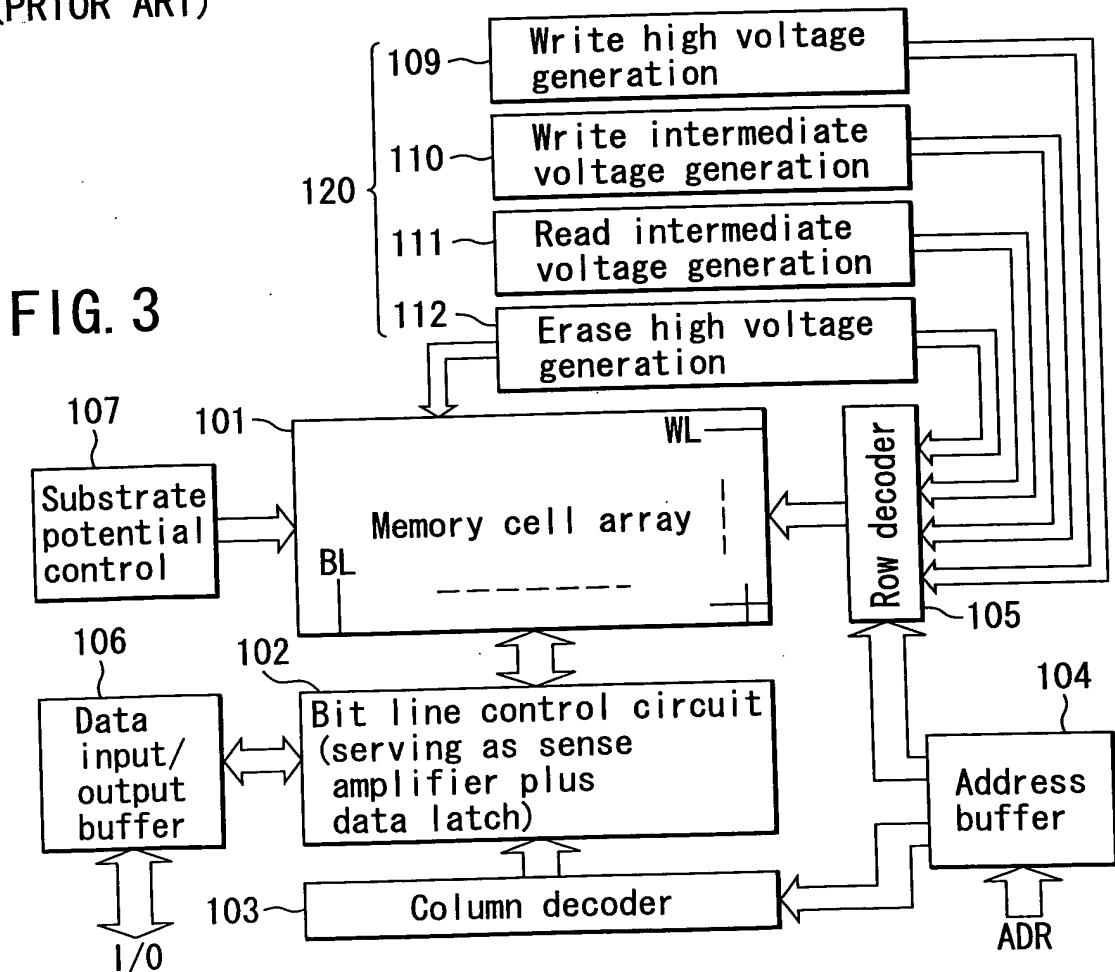
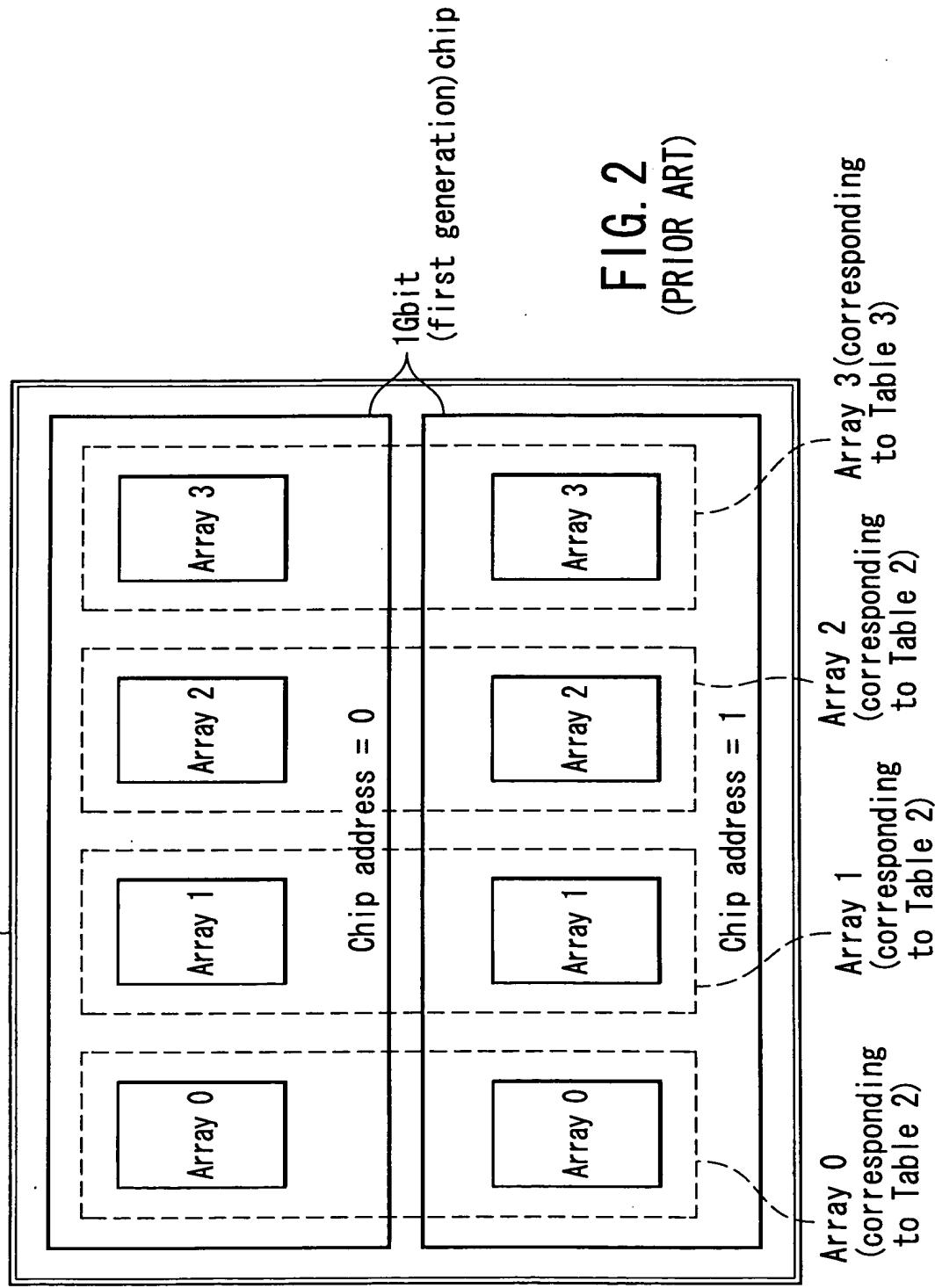


FIG. 1  
(PRIOR ART)



2 Gbit package product (first generation product is used)

2 Gbit package product



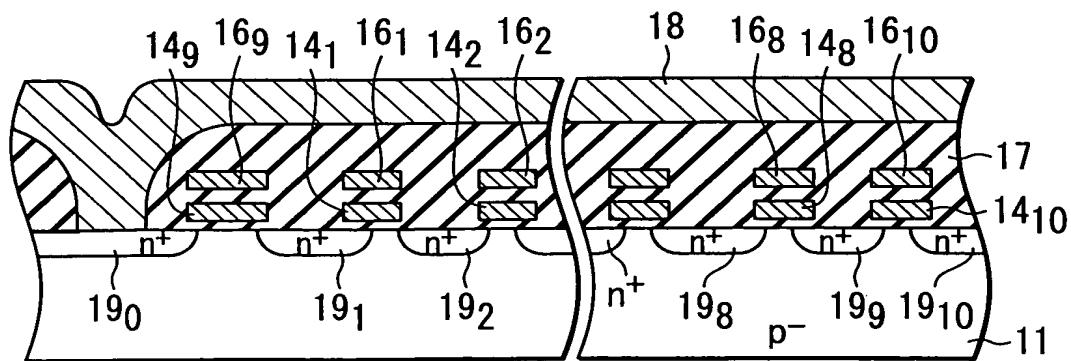
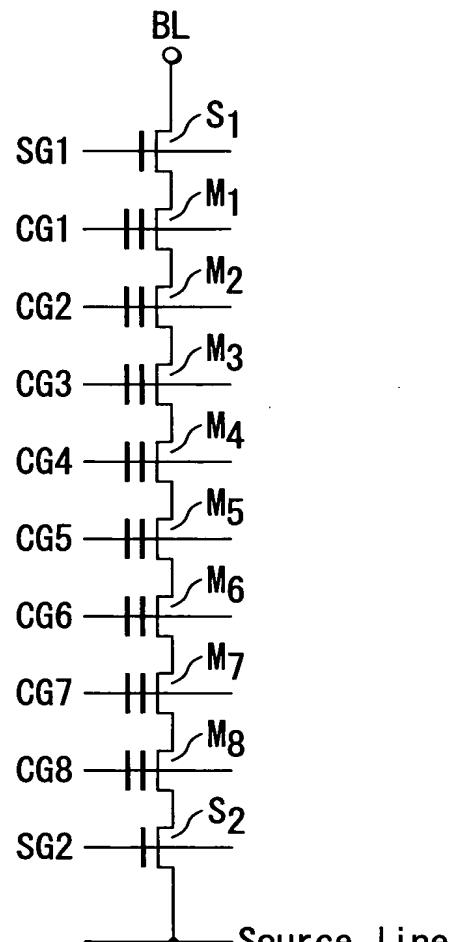
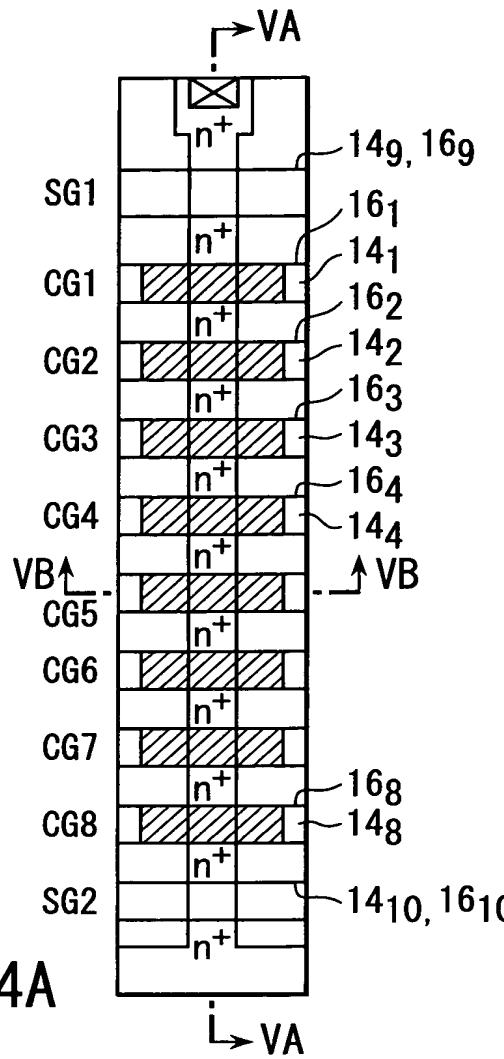


FIG. 5A

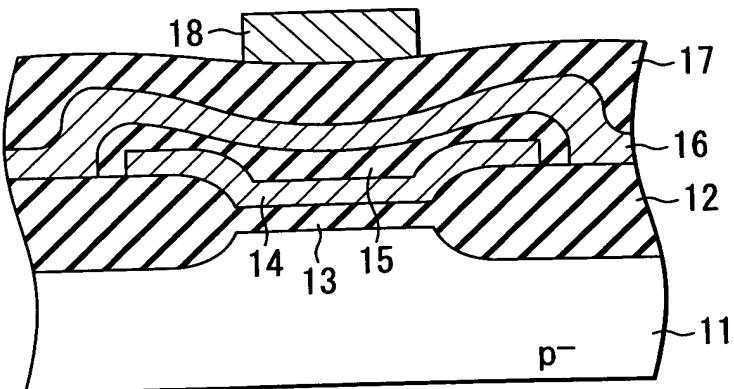


FIG. 5B

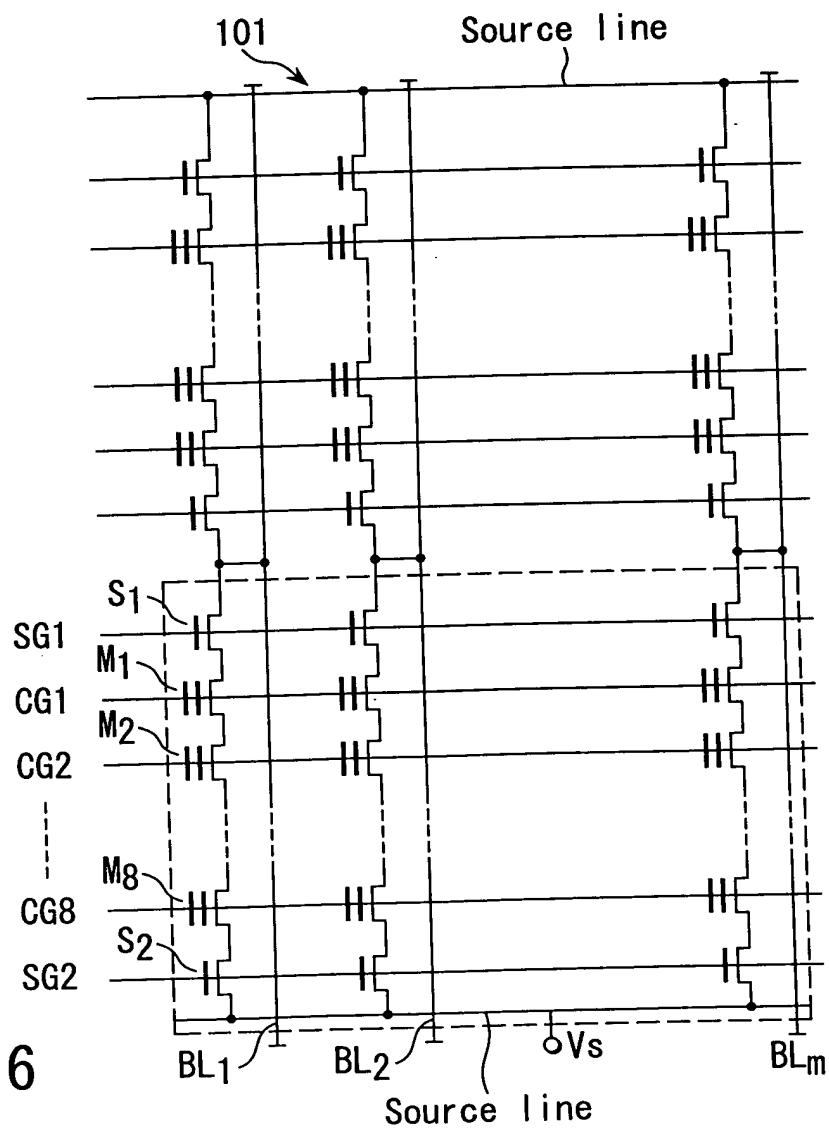


FIG. 6

Structure of 1 Gbit (first generation) chip

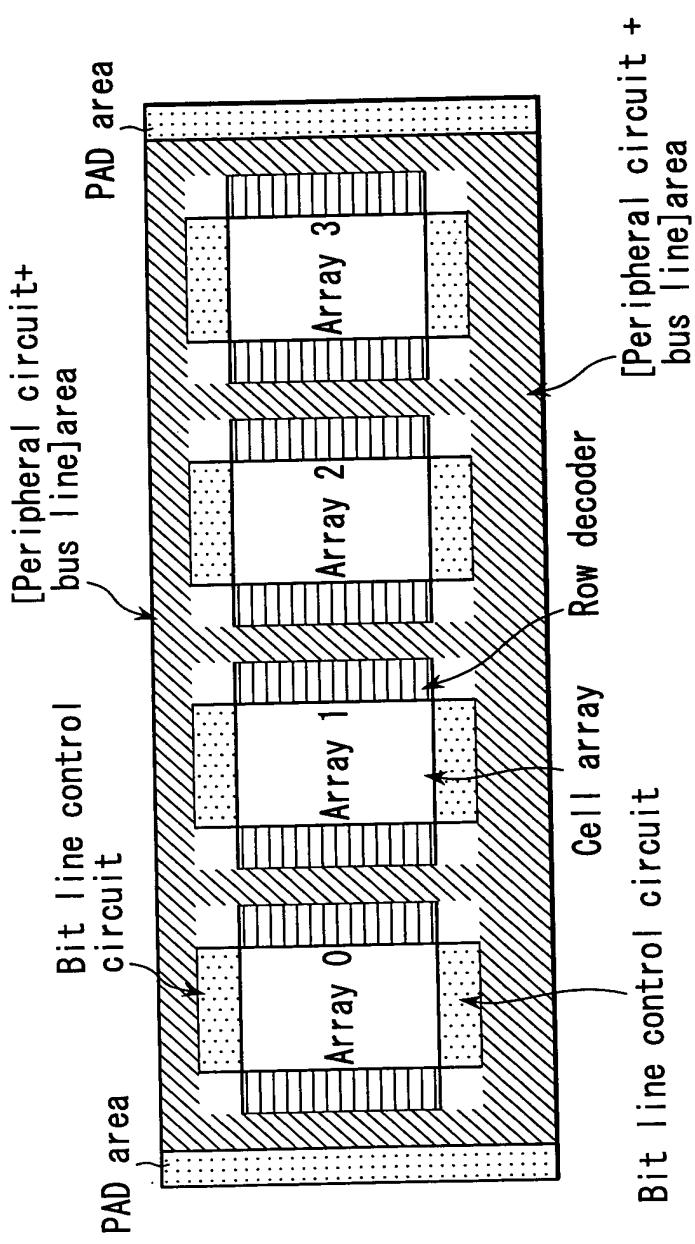


FIG. 7

Chip image when package product of FIG. 15 is seen from external device

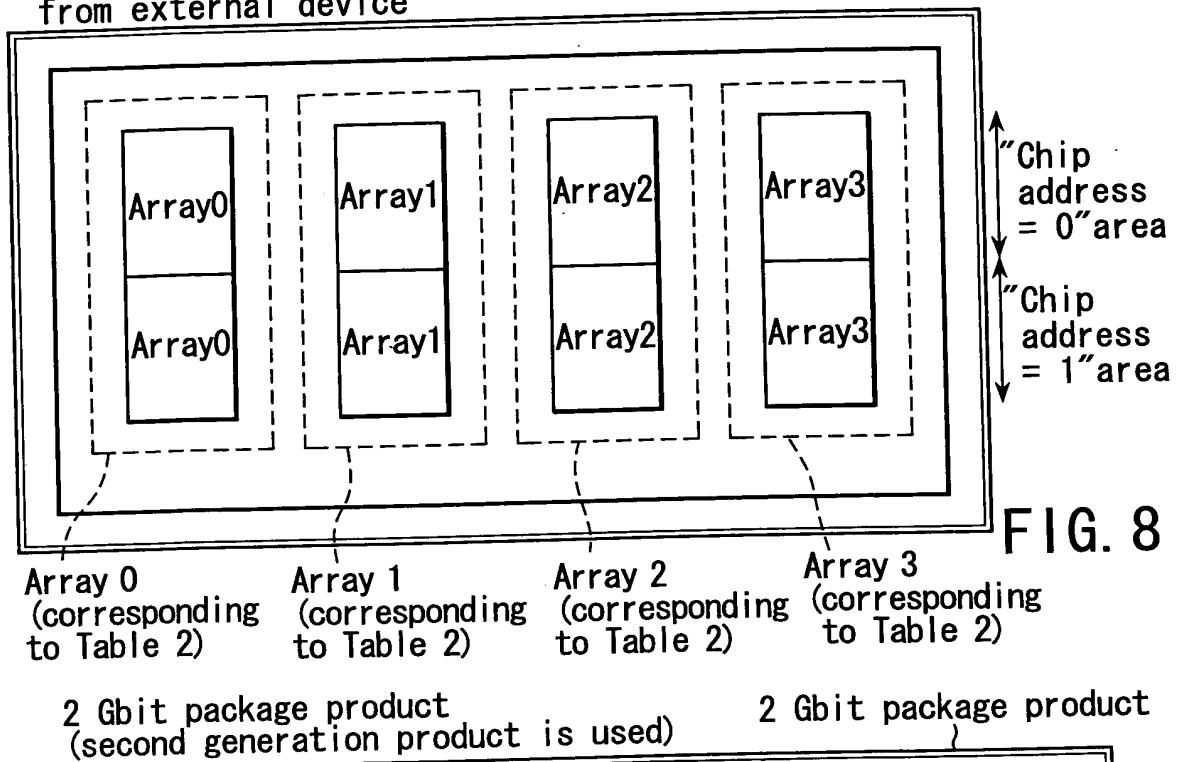


FIG. 8

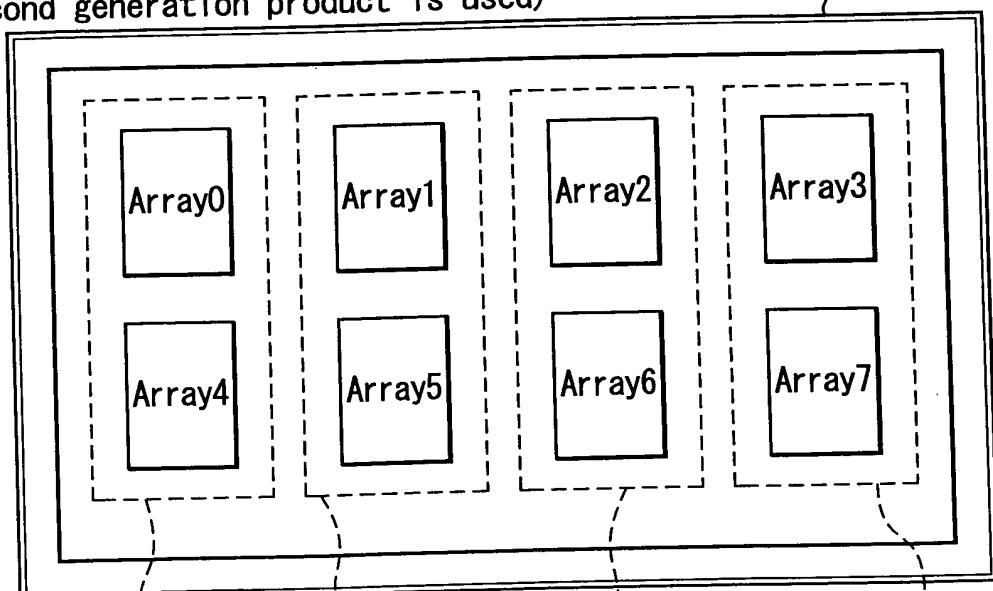


FIG. 9

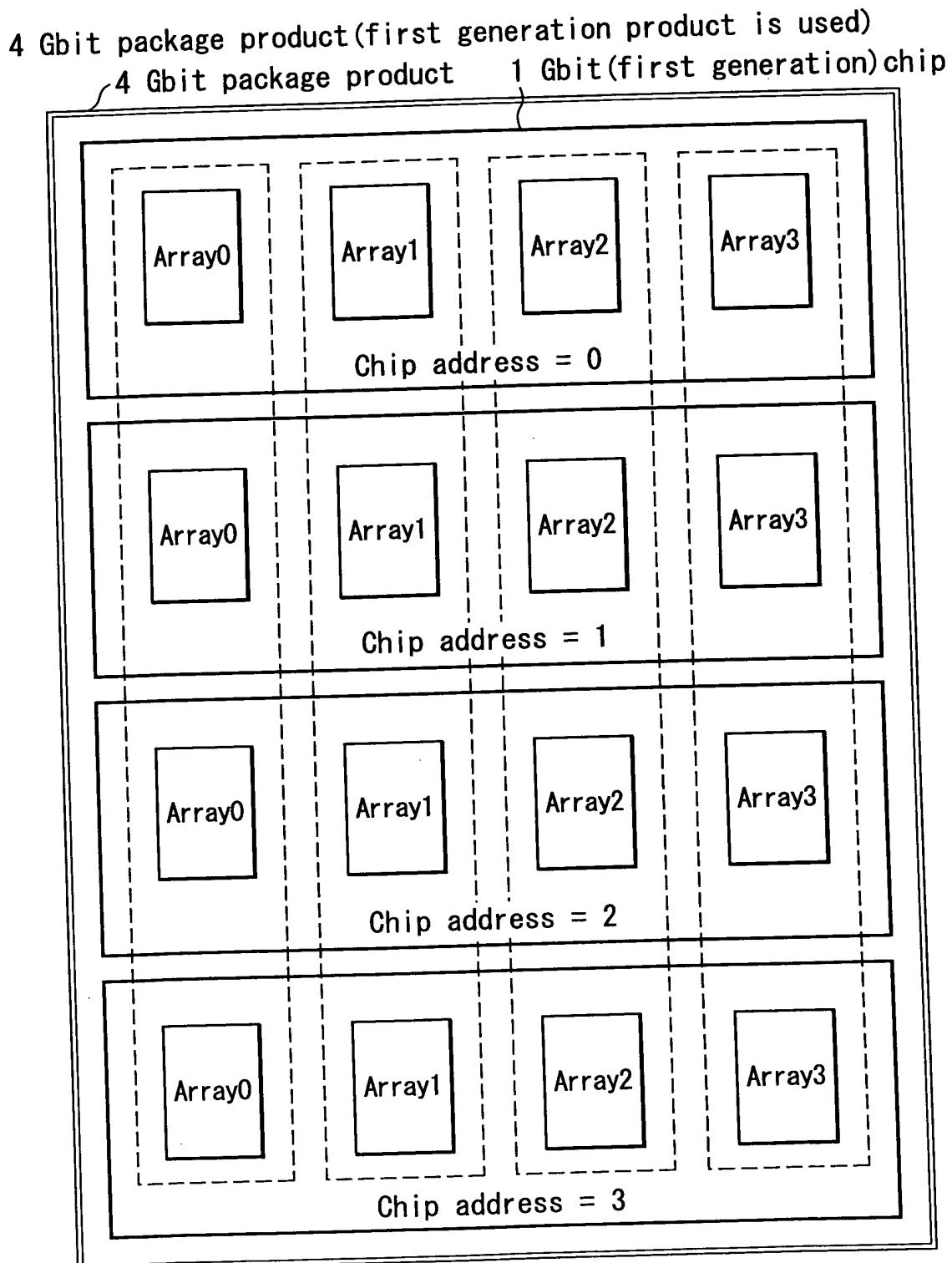


FIG. 10

Gbit package product  
(second generation product is used)

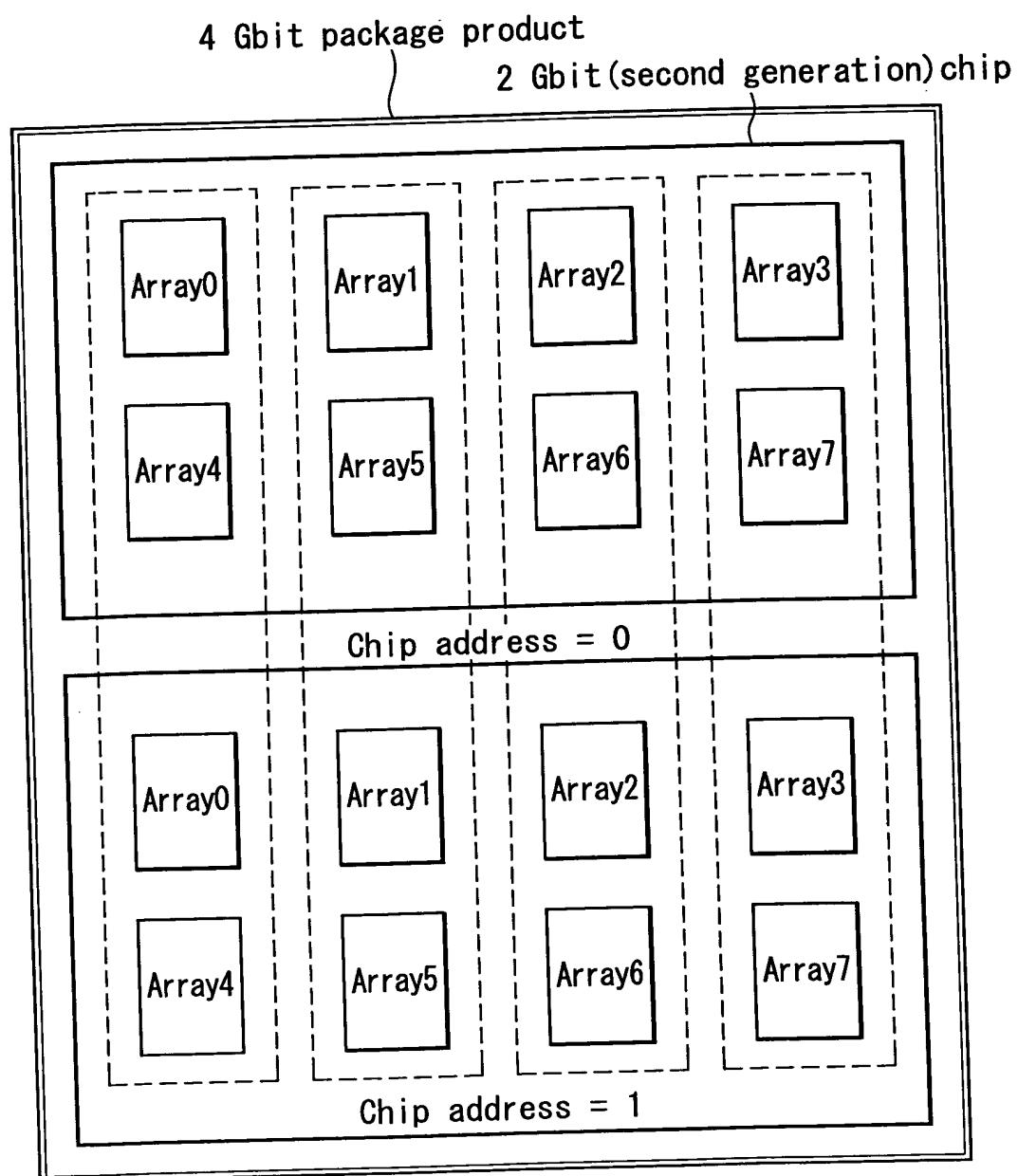


FIG. 11

4 Gbit package product  
(third generation product is used)

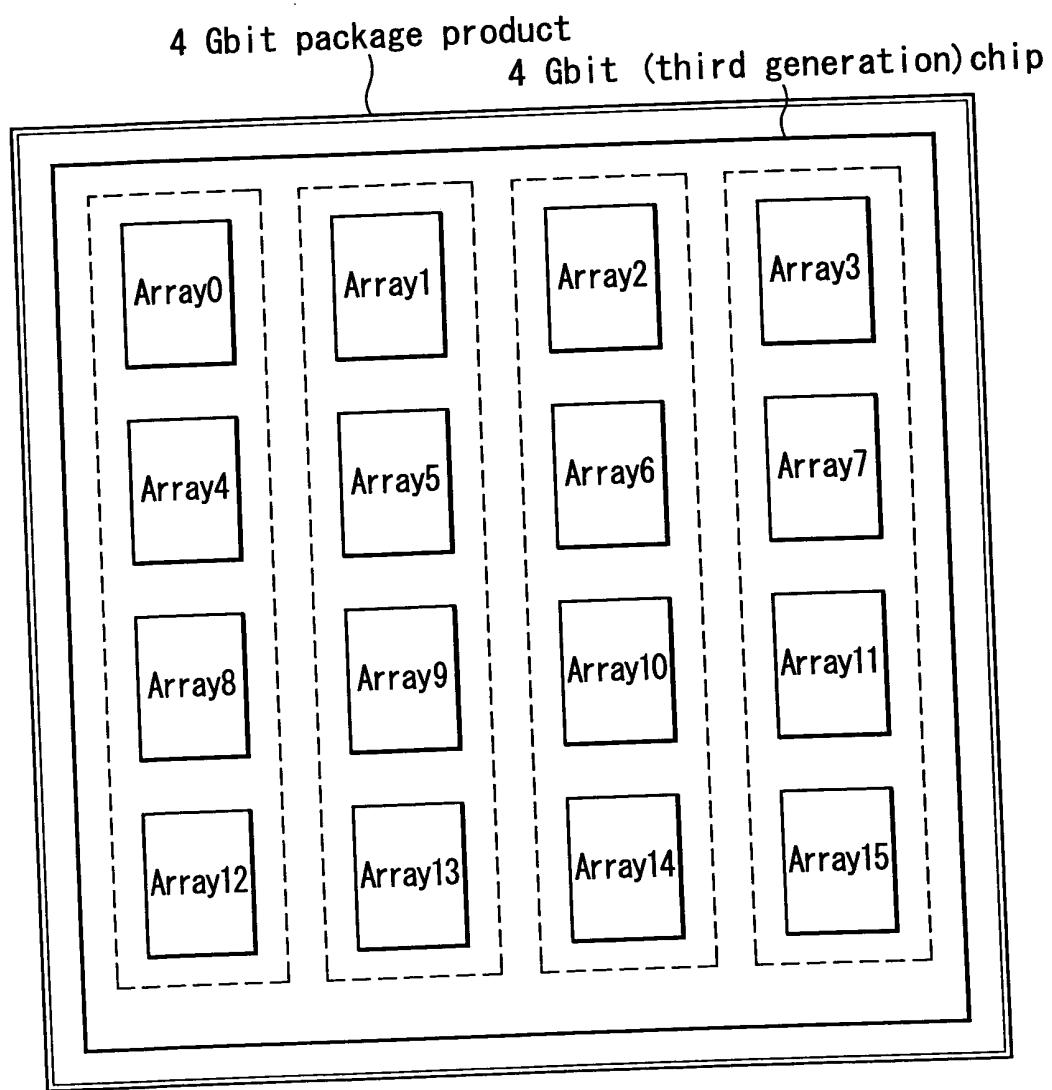


FIG. 12

4 Gbit package product  
(second generation product is used)

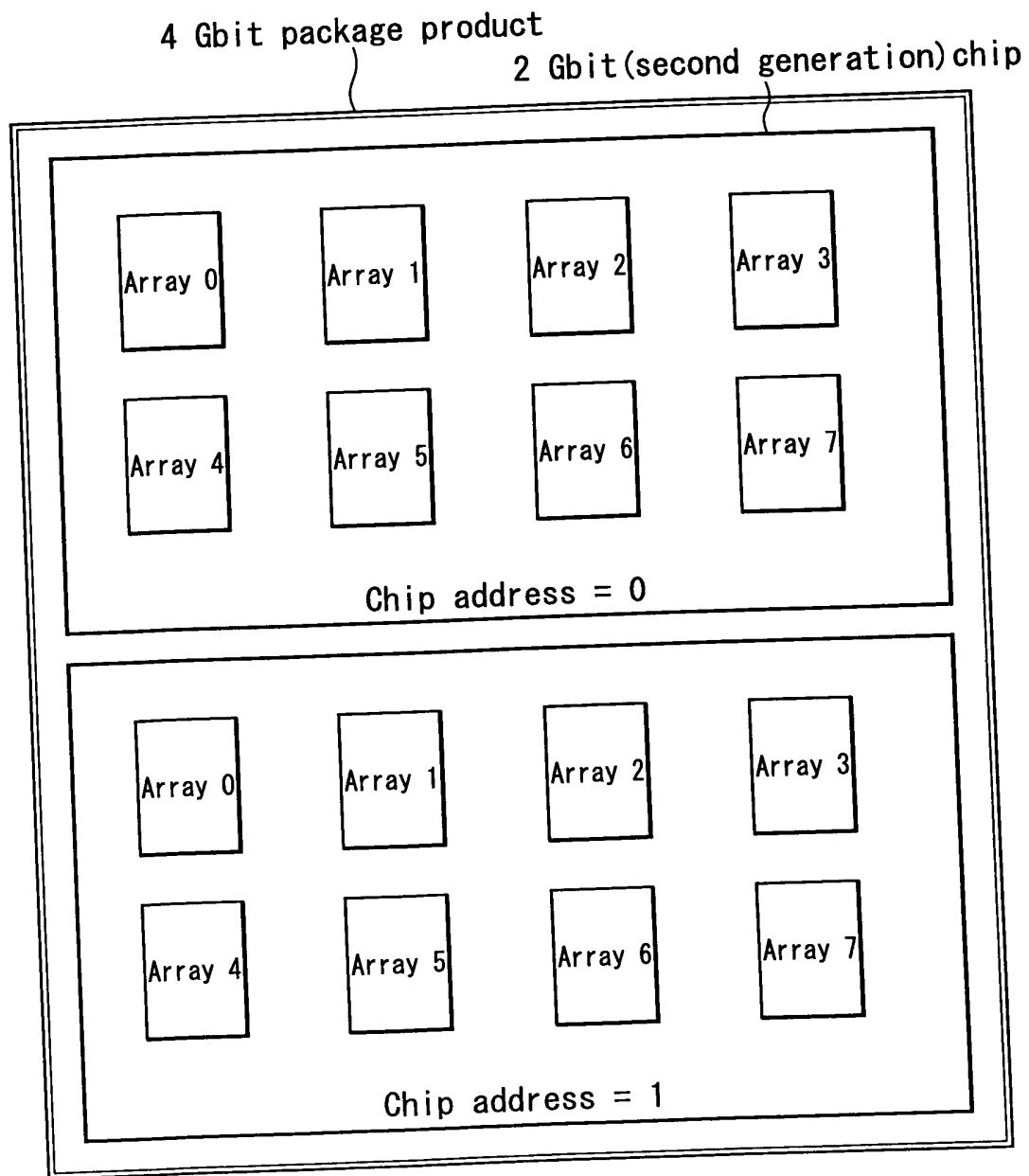


FIG. 13

Chip image when package product of FIG. 11 is seen from external device  
4 Gbit package product

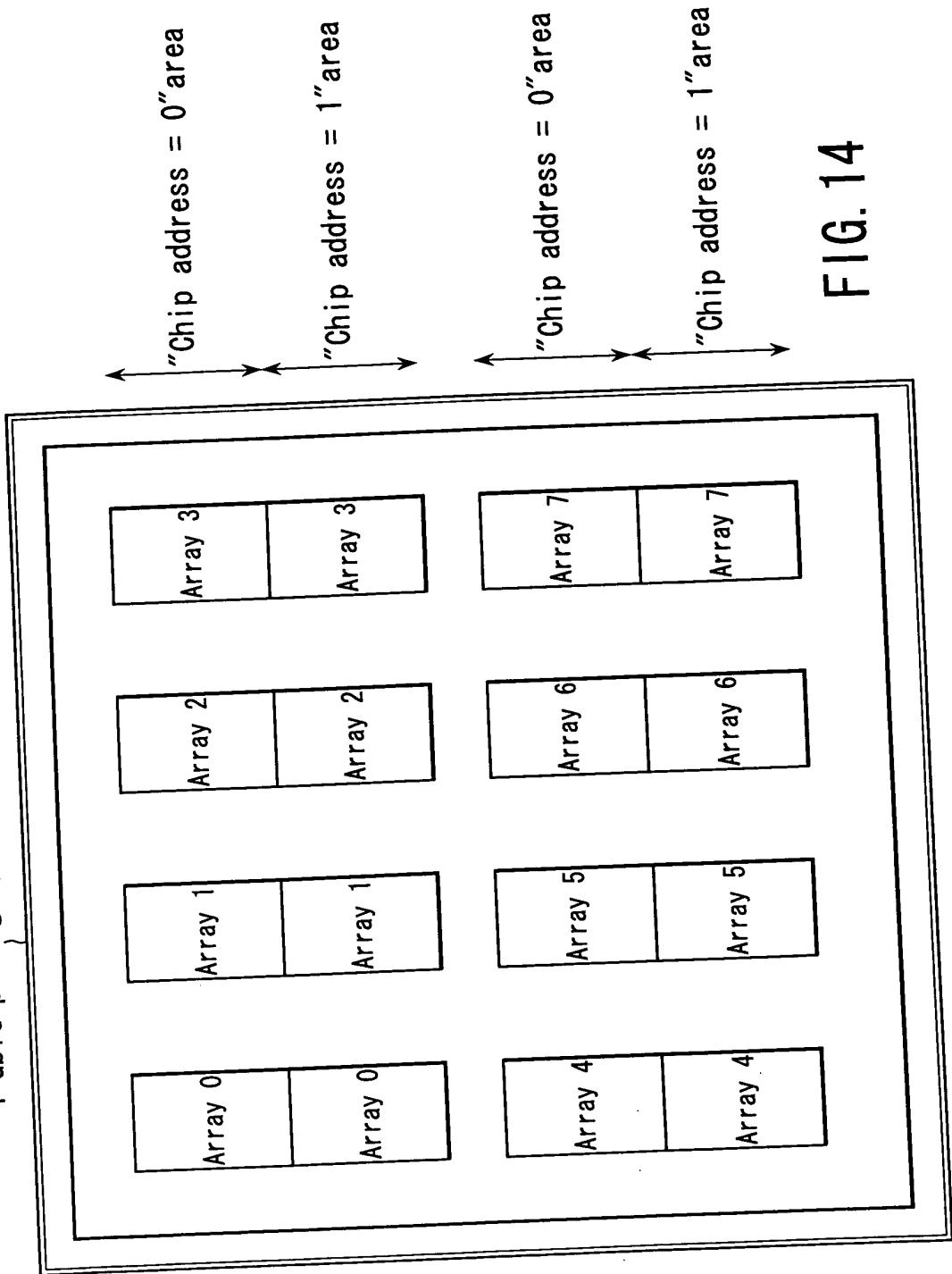


FIG. 14

4 Gbit package product (third generation product is used)

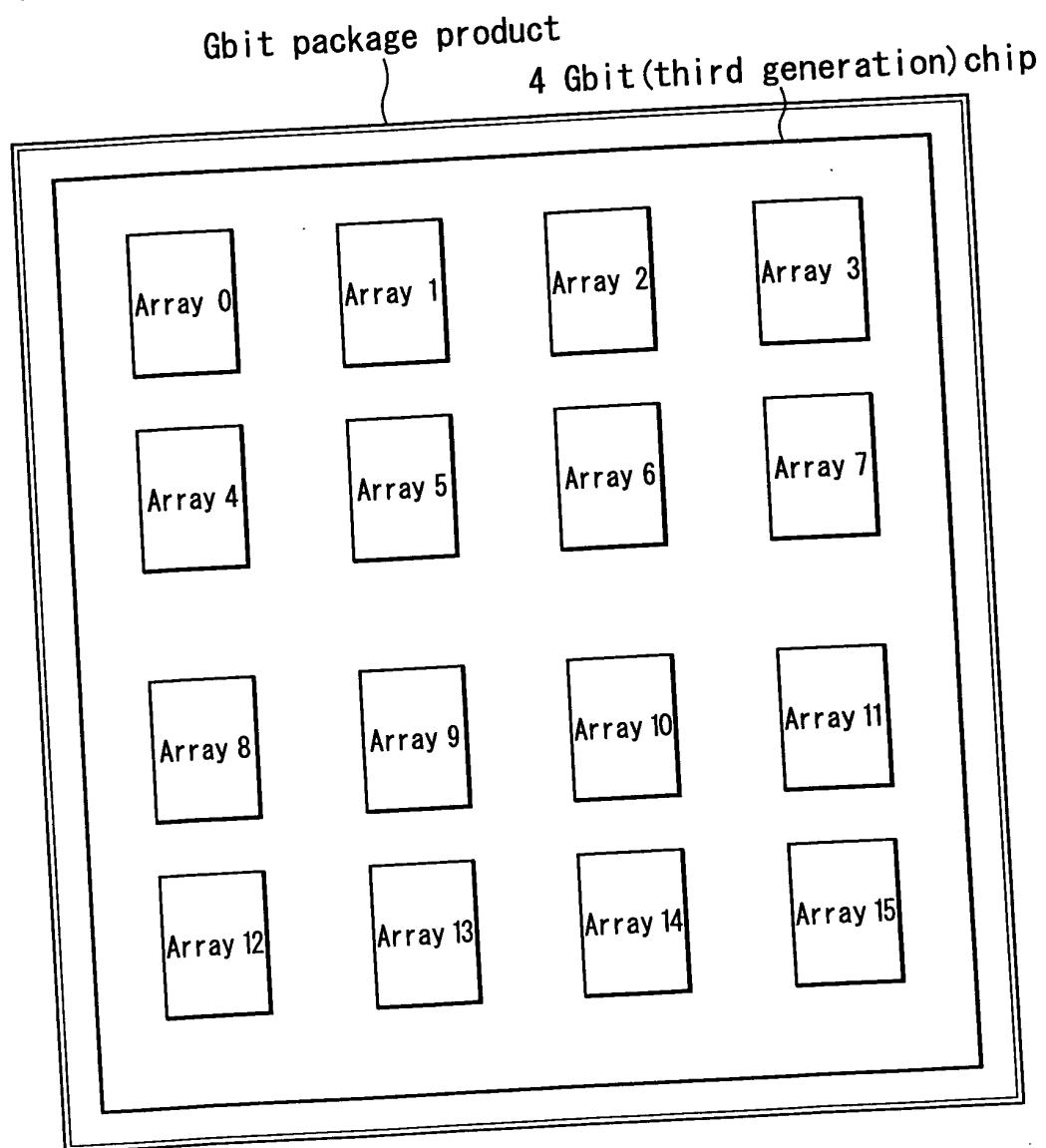


FIG. 15